

ABSTRACT OF THE DISCLOSURE

~~Sensors of physical quantities such as pressure or acceleration sensors and, more specifically, to the mounting of the active part of the sensor on a base bearing connection pins.~~ An active part of ~~the~~ a sensor is prepared. ~~This active part is formed, for example, by micro-machined silicon wafers bearing electronic elements, electrical conductors, and connection pads. A base is thus prepared, provided with, and pins, and the.~~ The pads are electrically connected to the pin ends by conductive elements. Then the wafer and the pin ends are plunged into an electrolytic bath to make an electrolytic deposit of conductive metal on the pin ends, the pads, and the conductive elements that connect them. Finally, this metal is oxidized or nitrized to ~~constitute~~ form an insulating coat on the pin ends, the pads, and the conductive elements that connect them. Such a sensor may find particular application ~~to~~ as a sensor of ~~pressure, stresses, acceleration, etc.,~~ designed to work in harsh environments.